

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-32 (canceled).

Claim 33 (withdrawn): A method of forming wiring lines on a board to form a printed circuit board, comprising the steps of:

- (a) forming the wiring lines of a predetermined uniform thickness; and
- (b) applying a conductive material on a first wiring line thereof so that the first wiring line has a first portion thicker than a second portion thereof.

Claim 34 (withdrawn): The method as claimed in claim 33, wherein the conductive material is applied on a second wiring line thereof spaced apart from the first wiring line in the step (b) so that the second wiring line has a third portion thicker than a fourth portion thereof.

Claim 35 (withdrawn): A method of forming wiring lines on a board to form a printed circuit board, comprising the steps of:

- (a) forming the wiring lines of a predetermined uniform thickness; and
- (b) grinding a first wiring line thereof so that the first wiring line has a first portion thinner than a second portion thereof.

Claim 36 (withdrawn): The method as claimed in claim 35, wherein a second wiring line thereof spaced apart from the first wiring line is ground in the step (b) so as to have a third portion thinner than a fourth portion thereof.

Claim 37 (currently amended): A method of forming a plurality of wiring lines on conductive material on a board having a core layer to form a printed circuit board, comprising:

- (a) forming said plurality of wiring lines on a surface of said core layer, having first and second portions, the plurality of wiring lines formed on said surface of said core having side walls of a uniform thickness in height relative to said surface of said core layer; and
- (b) etching the first portion of a first of said plurality of wiring lines, such that the first portion[[,]] has a planar surface completely across said first portion, joining said side walls, and is thinner in height relative to said surface of said core layer than the second portion.

Claim 38 (previously presented): The method as claimed in Claim 37, wherein a second of said plurality of said wiring lines is provided, spaced from said first wiring line of said plurality of wiring lines having said first and second portions, said second wiring line having third and fourth portions, and etching said second wiring line such that the third portion is thinner in height relative to said surface of said core layer than the fourth portion.